ABSTRACT

Method of fabricating semiconductor devices comprising the steps of: mounting a plurality of semiconductor chips (16) on a film carrier tape (30); sealing each one of the semiconductor chips (16) mounted on the film carrier tape (30) with epoxy resin (26); attaching an individual stiffener (28) to the film carrier tape (30) at a position corresponding to each one of the semiconductor chips (16); forming a plurality of bumps (14) on the film carrier tape (30) at a position corresponding to each one of the semiconductor chips (16); and punching out the film carrier tape (30) into separate pieces of insulating film (12) after above-described steps. In this method, each step is carried out on the film carrier tape (30) running between supply and take-up reels.